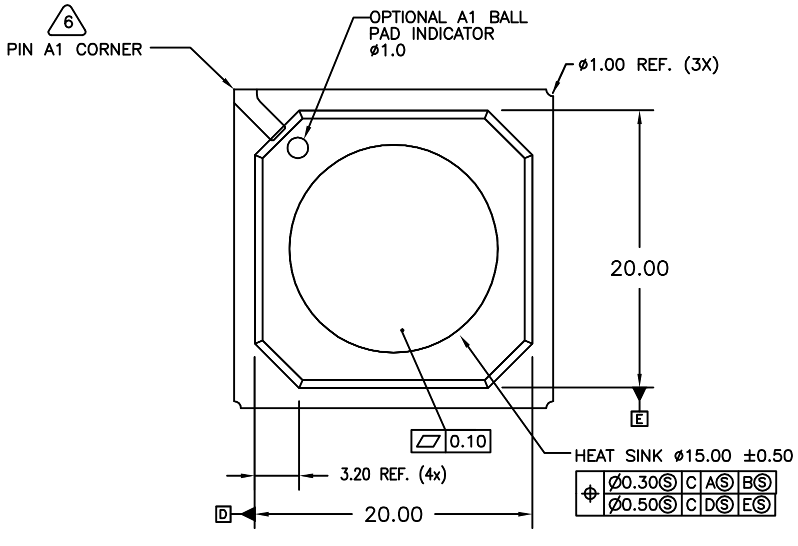
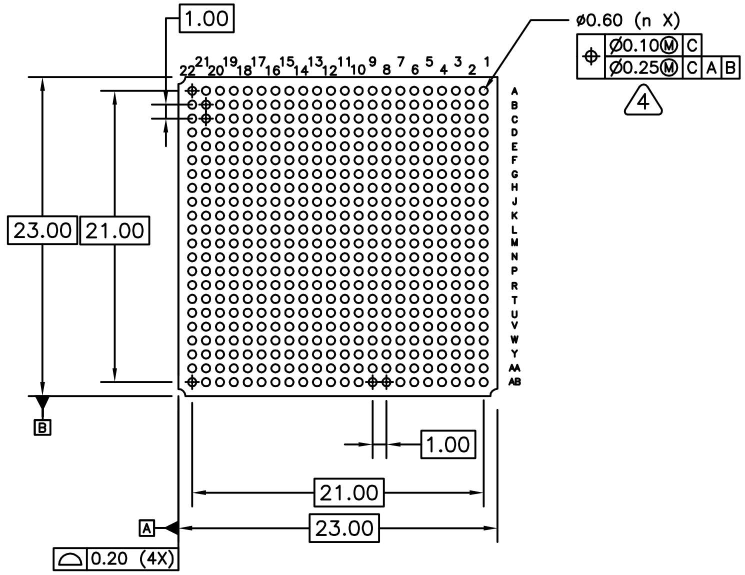
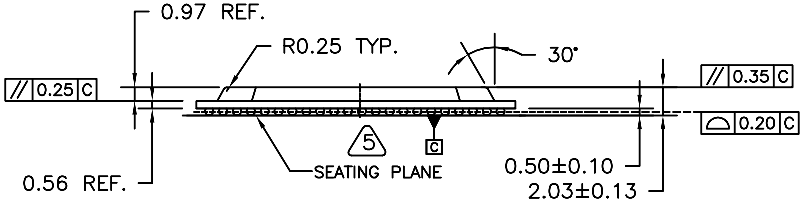


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM C
5. PRIMARY DATUM C AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO LEADED (-), LEAD FREE (+) PKG. CODES.
8. PACKAGE CODE: V484H-1
V484H-3

-DRAWING NOT TO SCALE-

TITLE: PACKAGE OUTLINE, 484 BALLS PBGA W/HEAT SINK, 23.0x23.0x2.03mm, 1.00mm PITCH, 4 LAYER			
APPROVAL	DOCUMENT CONTROL NO. 21-0367	REV. B	1/1